【Press Release】

LITEON Powers AI from Cloud to Edge at electronica 2026

2026/11/5

✦ News Summary

- LITEON participates in electronica 2026 under the theme “LITEON Powers AI,” with a focus on “From Cloud to Edge.” Bringing together technologies from across its business portfolio, LITEON showcases key capabilities spanning AI data center infrastructure, edge computing and intelligent applications, including power and energy management, networking and optical communication technologies, demonstrating the strength of its “One LITEON” cross-domain technology integration.
- Complete From Grid to Chip power architecture: LITEON integrates energy storage, rack-level power delivery, server power and near-chip power conversion, bringing together key technologies including 800 VDC, Power Shelves, power modules and DC/DC conversion to enhance power efficiency and energy resilience for AI data centers.
- Edge AI intelligence at the edge: LITEON integrates power, networking, 5G, Edge AI Vision and intelligent sensing solutions to connect cloud infrastructure with edge devices, accelerating AI computing and real-time sensing across smart buildings, healthcare, retail and industrial automation.
- Next-generation optical communication and intelligent photonics: LITEON focuses on high-speed optical interconnects for AI data centers while extending its capabilities into intelligent sensing, advanced optics and AR optics, integrating technologies from key components and optical modules to system-level applications.

LITEON Technology (2301) heads to electronica 2026 in Munich, Germany, from November 10 to 13, continuing its “LITEON Powers AI” theme and bringing together technologies from across its business portfolio. Across two dedicated exhibition areas, “AI Power” and “Intelligent Photonics,” LITEON showcases key technologies spanning power and energy management, networking and optical communications for AI infrastructure and edge computing, alongside applications including intelligent surveillance, intelligent sensing and AR optics. The showcase reflects LITEON’s “One LITEON” strategy and “From Cloud to Edge” vision, demonstrating its integrated technology and system capabilities across cloud infrastructure and edge applications.

From Grid to Chip: Building a Complete Power Architecture for AI Data Centers

As AI computing scales and power density continues to rise, the data center challenge extends beyond increasing compute capacity to deliver energy to the compute core with greater efficiency and stability. LITEON presents a comprehensive power architecture spanning energy storage, rack-level power delivery, server power and near-chip power

conversion. Key technologies on display include 800 VDC, high-power Power Shelves, modular power solutions, 800V Power Bricks, 50V Power Bricks, Intermediate Bus Converter (IBC) modules and Voltage Regulator Modules (VRMs), together with other critical DC/DC power conversion technologies.

LITEON also showcases high-power magnetic components for AI power systems, energy storage and industrial power conversion. From energy supply and rack-level power distribution to server power and precise power delivery at the chip level, LITEON demonstrates its comprehensive power and energy management capabilities for high-density AI computing.

Extending AI from Cloud to Edge with Power, Connectivity and Intelligent Sensing to Accelerate Edge AI in Real-World Applications

As AI extends beyond data centers and moves closer to where data is generated and used, computing, connectivity and sensing capabilities increasingly expand into enterprise, industrial and intelligent environments. LITEON showcases a broad portfolio of power and connectivity technologies supporting AI infrastructure, enterprise networks, industrial automation and edge computing, together with solutions across networking, 5G, Edge AI Vision and intelligent sensing. By bringing together the power and connectivity capabilities required across cloud infrastructure and edge devices, LITEON enables AI computing and real-time visual intelligence across applications including smart buildings, healthcare, retail, smart offices and industrial automation. This enables data to be processed, analyzed and acted upon locally, accelerating AI from cloud computing into real-world applications.

Advancing High-Speed Optical Interconnects for Next-Generation AI and Intelligent Photonics

As AI computing and clusters continue to scale, data centers require greater bandwidth, lower latency and more efficient data transmission, making high-speed optical interconnects increasingly important to next-generation AI infrastructure. LITEON showcases its high-speed optical communication technologies for AI data centers while extending its capabilities into intelligent sensing, advanced optics and AR optics. By continuously integrating technologies from key components and optical modules through system-level applications, LITEON advances its “Digital Photonics Integrator” vision and demonstrates its integrated capabilities spanning core technologies through diverse applications.

From power, energy management and high-speed optical connectivity for AI data centers to enterprise networking, edge computing and intelligent sensing applications, LITEON continues to integrate core technologies across its businesses and extend the capabilities of “One LITEON” from cloud to edge. By addressing the increasing convergence of computing, power, optical connectivity and sensing in the AI era, LITEON helps customers build more efficient, reliable and scalable AI infrastructure and intelligent applications. Welcome industry partners and visitors from around the world to visit LITEON at electronica 2026. For more information, please visit: https://www.liteon.com/en/solutions/overview.

LITEON Technology at electronica 2026:

- Date: November 10 – 13, 2026
- Venue: Messe München, Germany
- AI Power Booth: #124, Hall A5
- Intelligent Photonics Booth: #337, Hall B5



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